

JC832 U.S. PTO
10/021257



U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM 10021257	FILING DATE 12/19/2001	CLASS 25	SUBCLASS 174	GAU 2841	EXAMINER
**APPLICANTS: Chinda Akira; Matsuura Akira;					
**CONTINUING DATA VERIFIED:					
** FOREIGN APPLICATIONS VERIFIED: JAPAN 2000-389958 12/19/2000					
PG-PUB DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO			
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		035532-0118			
Verified and Acknowledged Examiners's initials					
TITLE : Wiring board, semiconductor device, and process for production of wiring board					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs.Drwg. Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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